

FIG. 1A

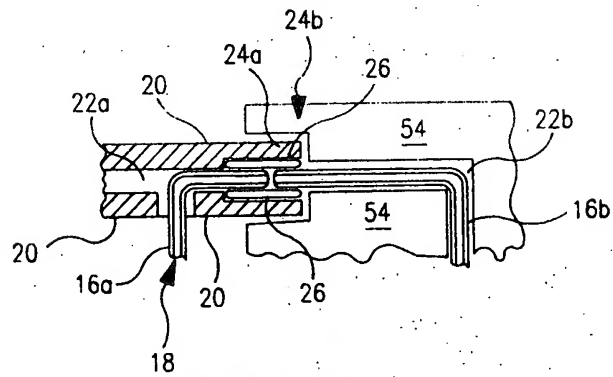


FIG. 1B

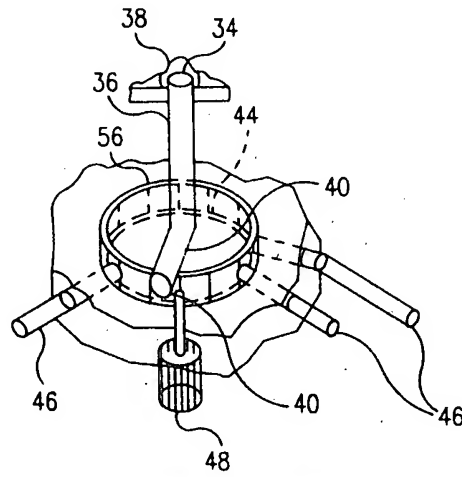


FIG. 1C

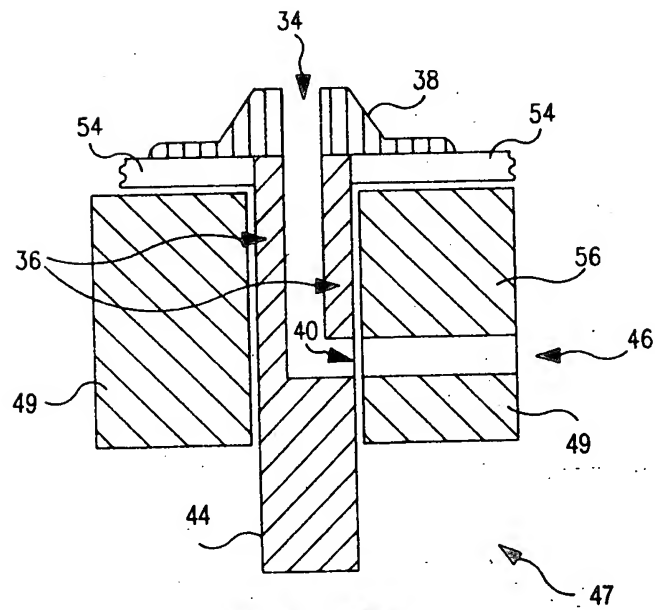


FIG. 1D

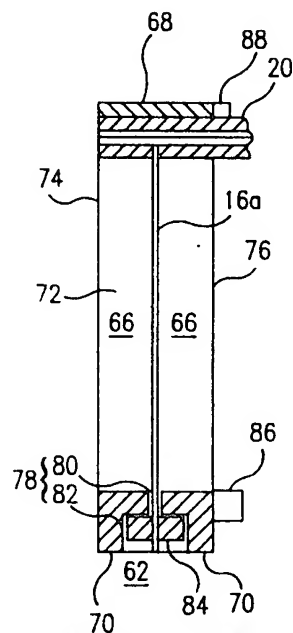


FIG. 2A

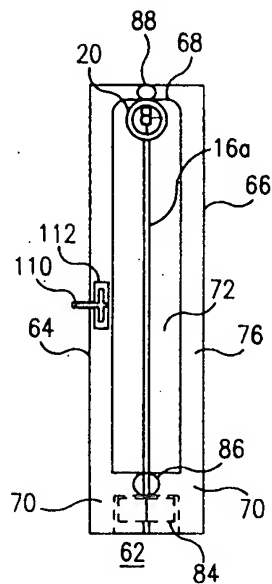


FIG. 2B

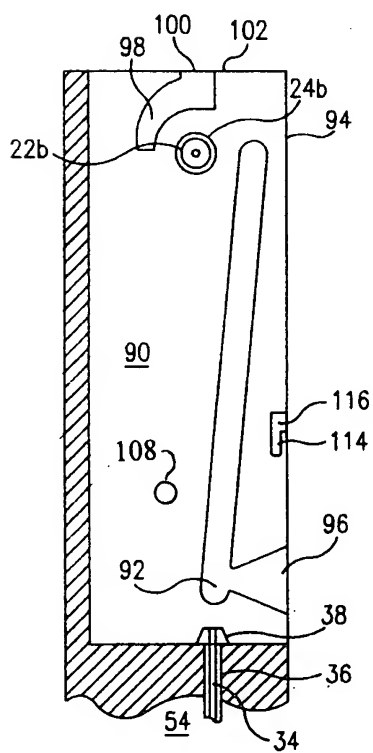


FIG. 3

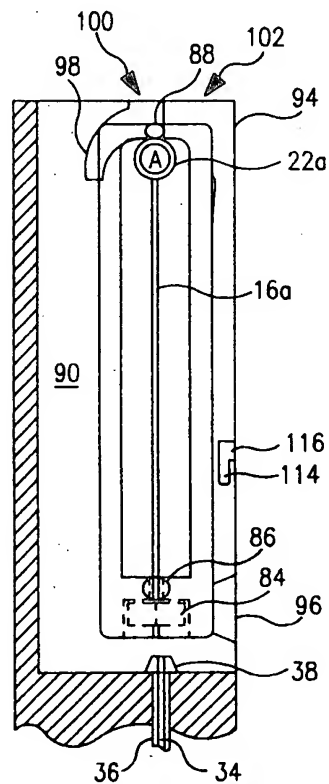


FIG. 4

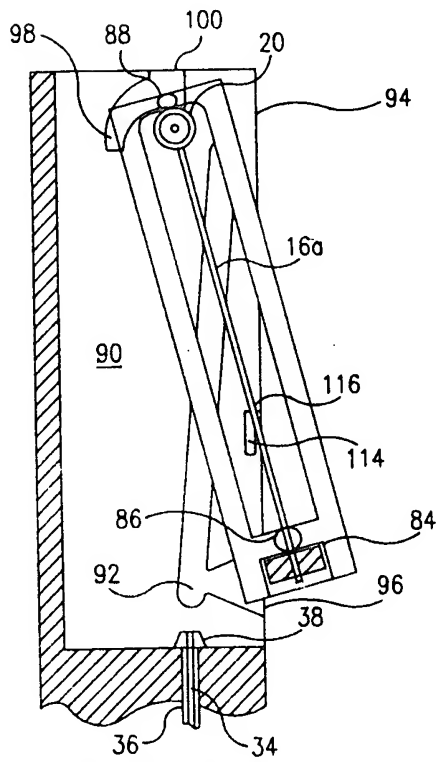


FIG. 5A

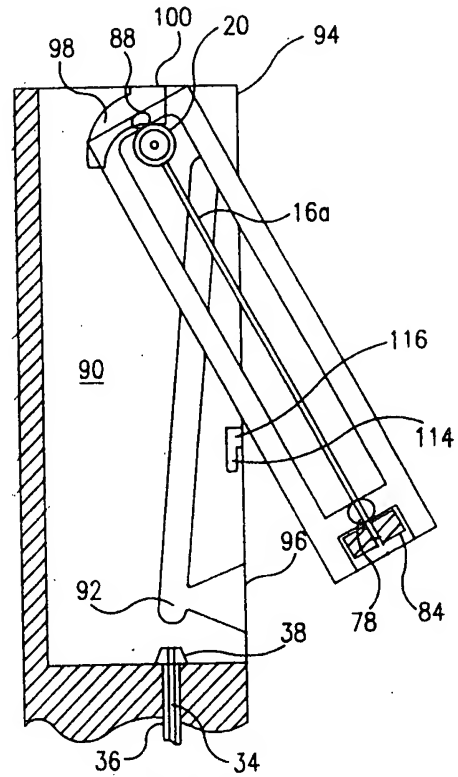


FIG. 5B

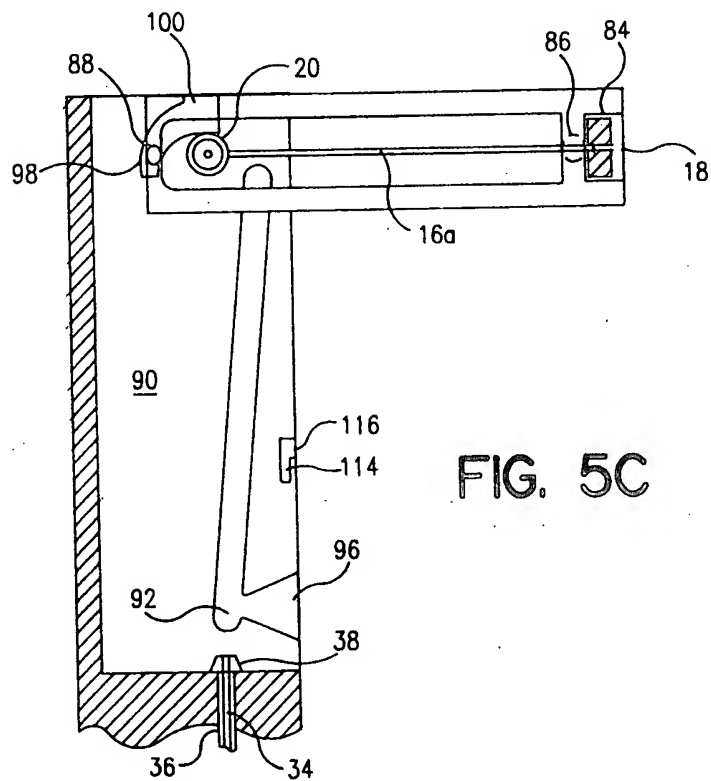


FIG. 5C

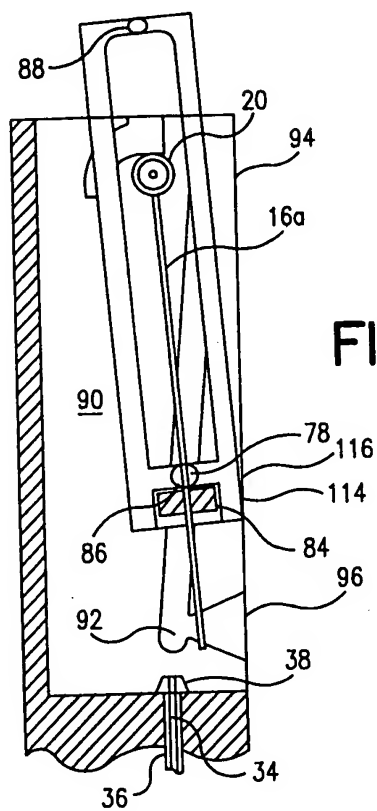


FIG. 6A

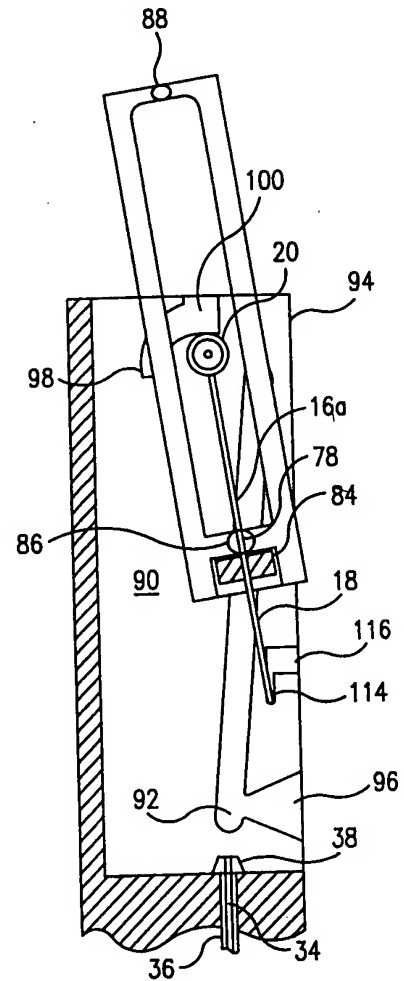


FIG. 6B

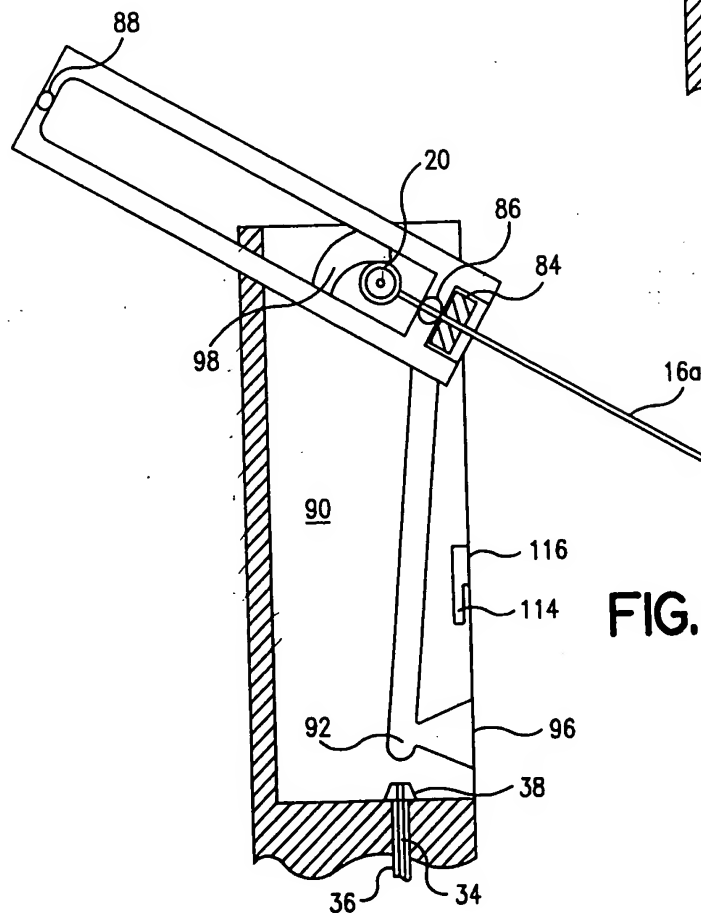


FIG. 6C

A cross-sectional view of a device assembly. The assembly consists of several layers and components. A central layer is labeled 120. Below it is a layer labeled 122, which contains two rectangular regions labeled 126. Above layer 120 is a thin layer labeled 124. To the right of the central assembly is a layer labeled 128, followed by a layer labeled 130, and then a layer labeled 132. The entire assembly is supported by a base layer labeled 118. A component labeled 134 is shown on the left side, partially overlapping the central assembly. A vertical arrow labeled 118 points upwards towards the central assembly.

FIG. 8C

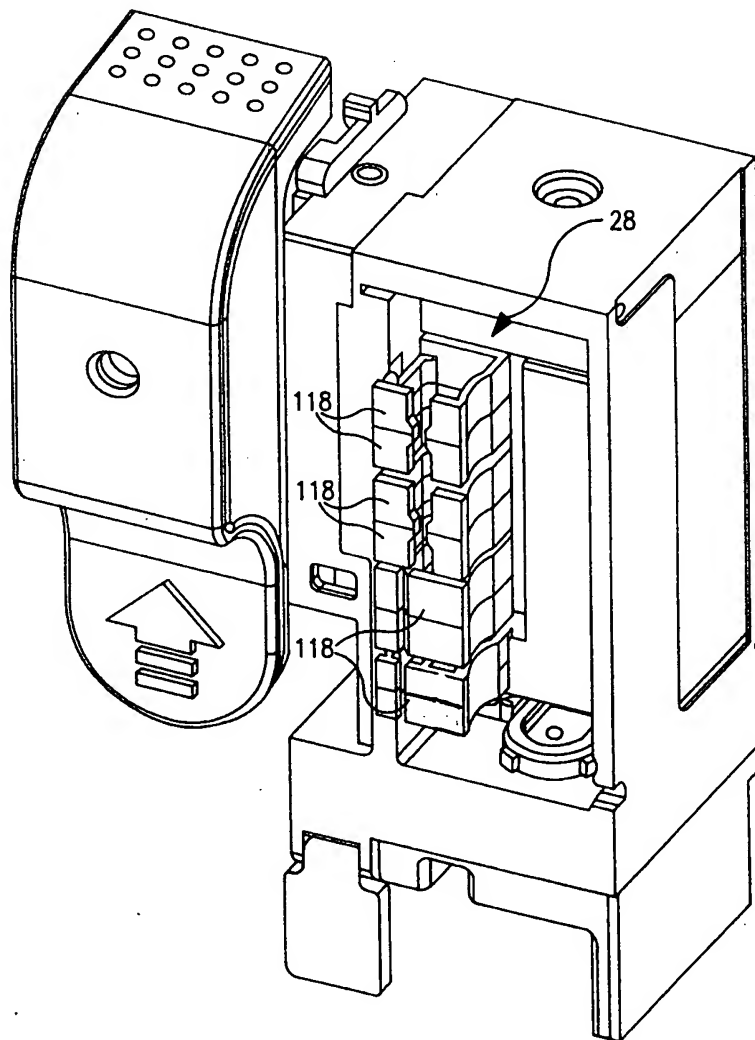
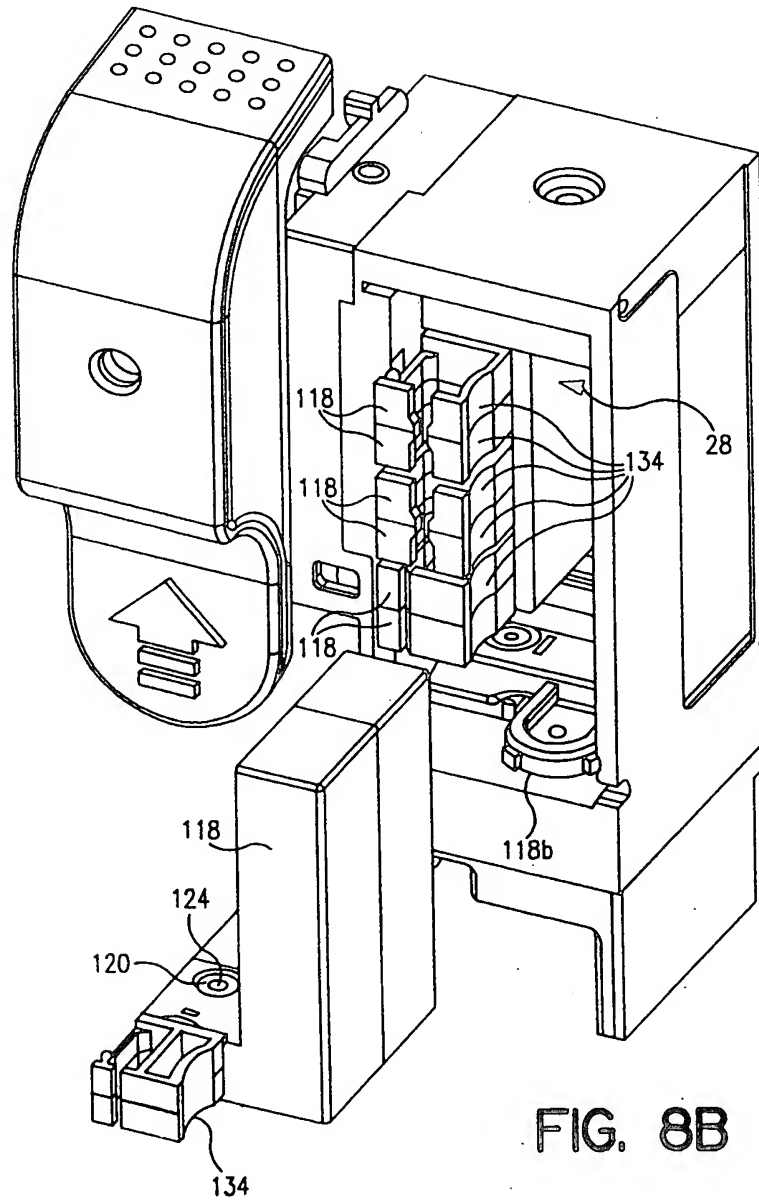


FIG. 8A





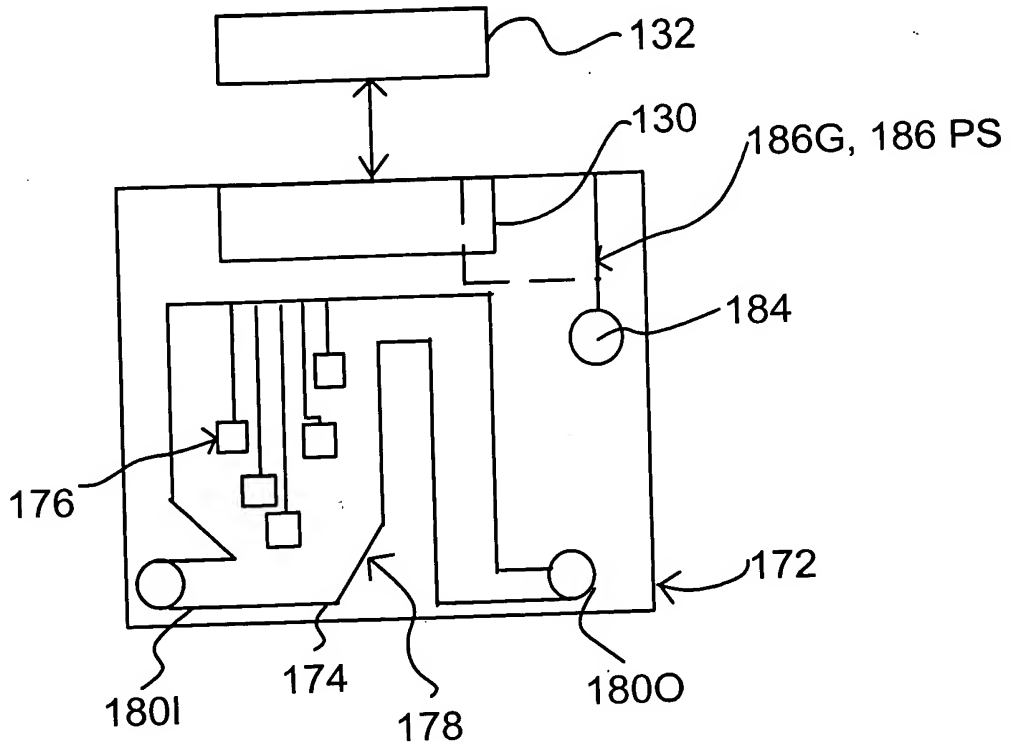


FIG. 8D

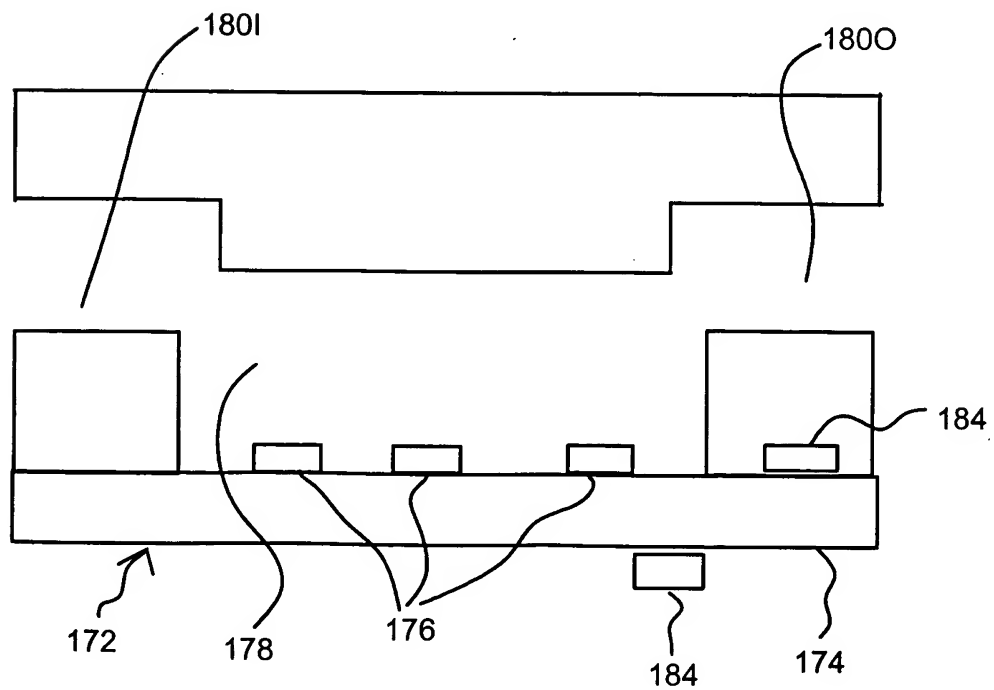


FIG. 8E

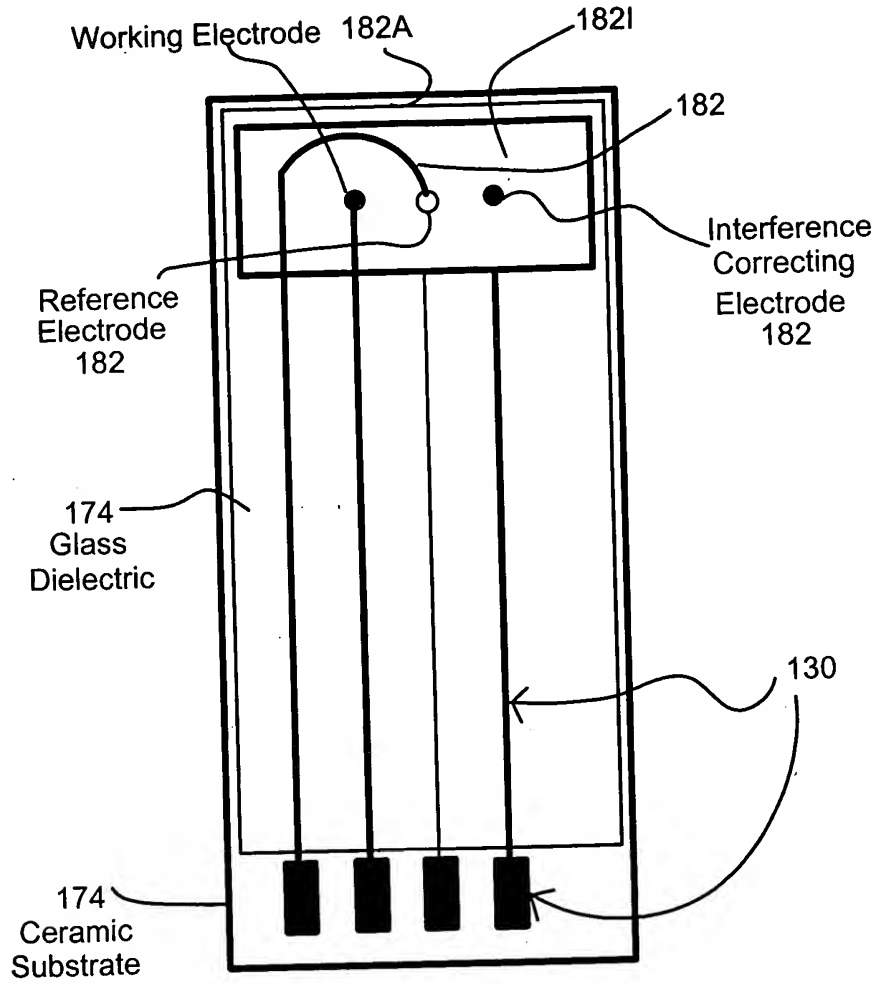


FIG. 8F

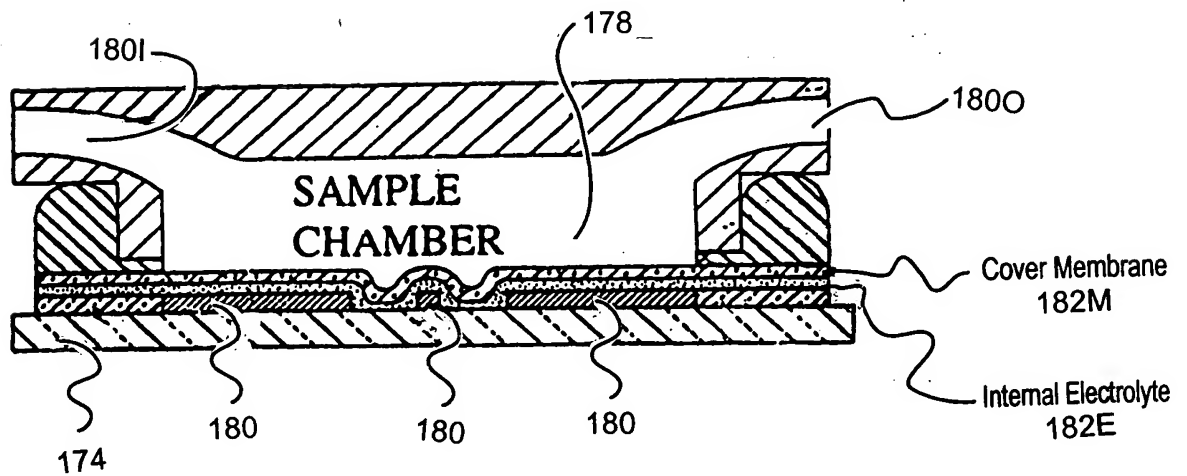


FIG. 8G

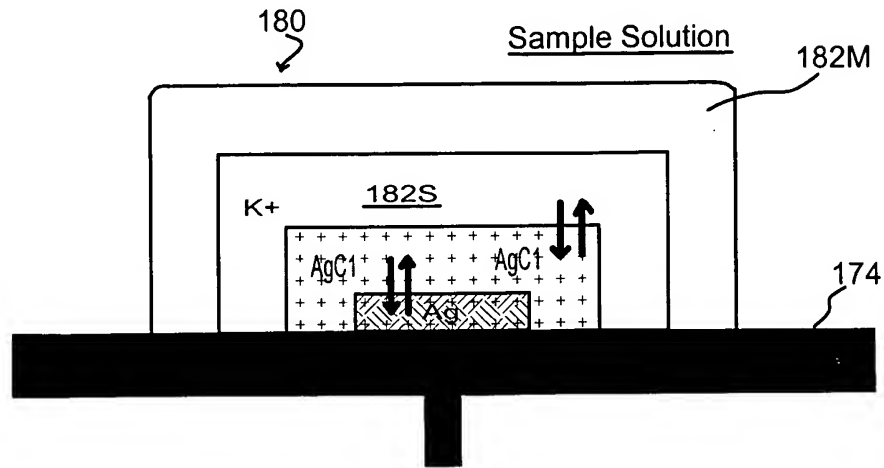


Fig. 8H

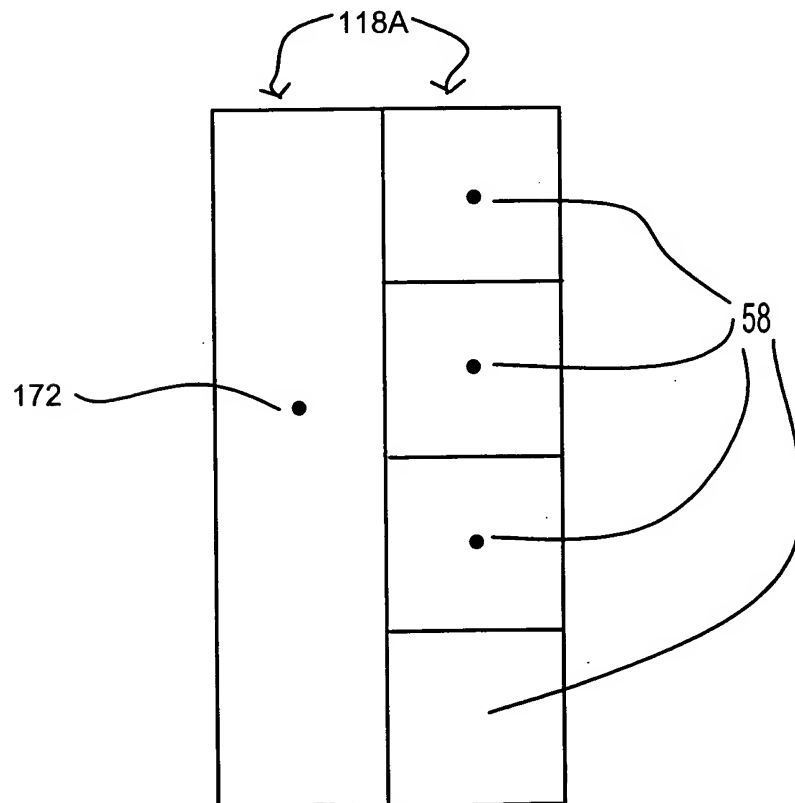


Fig. 8I

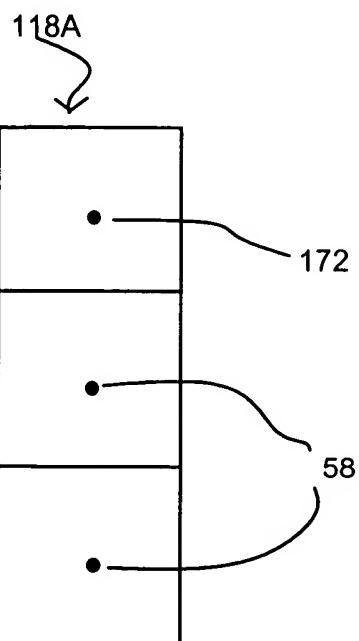


Fig. 8K

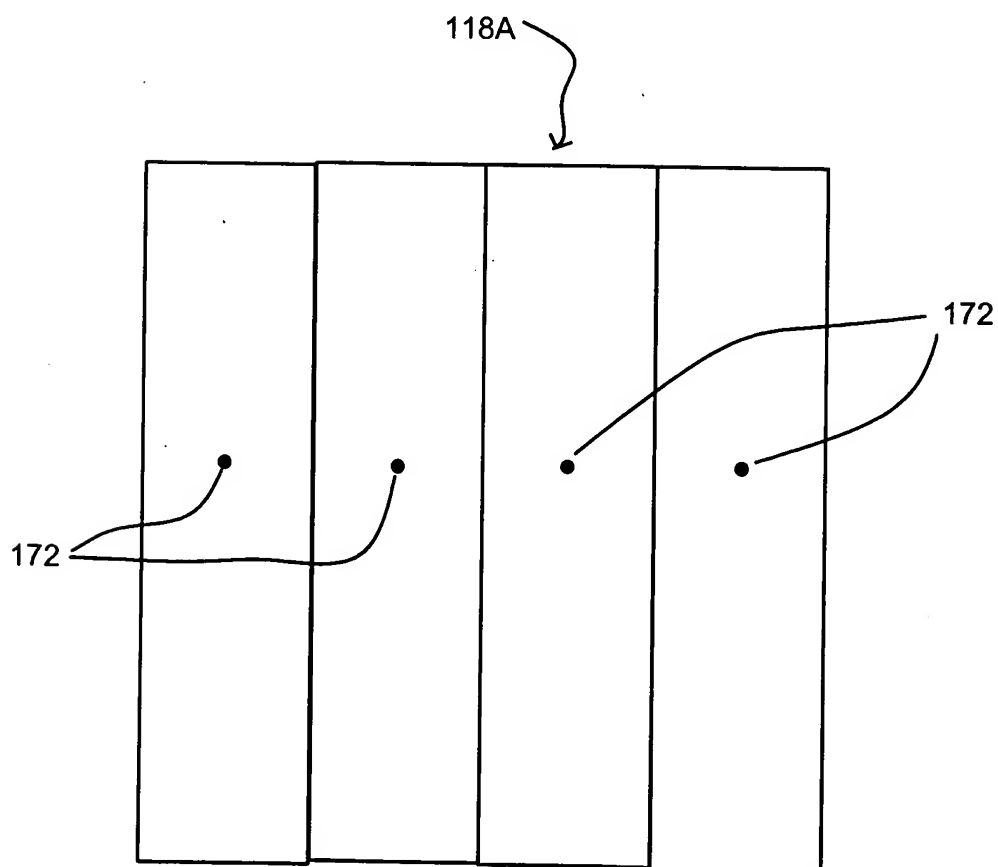


Fig. 8J

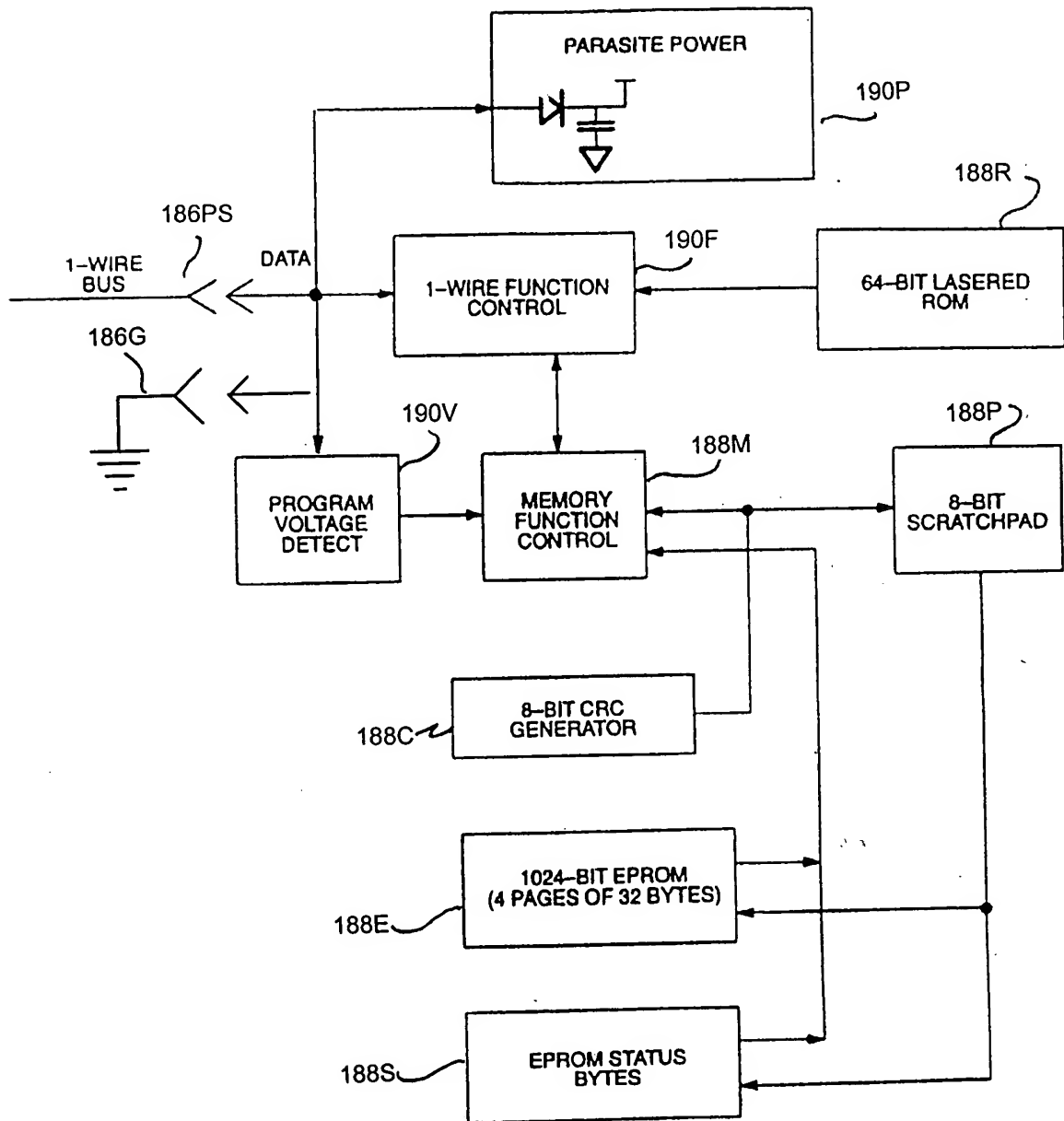


Fig. 8L

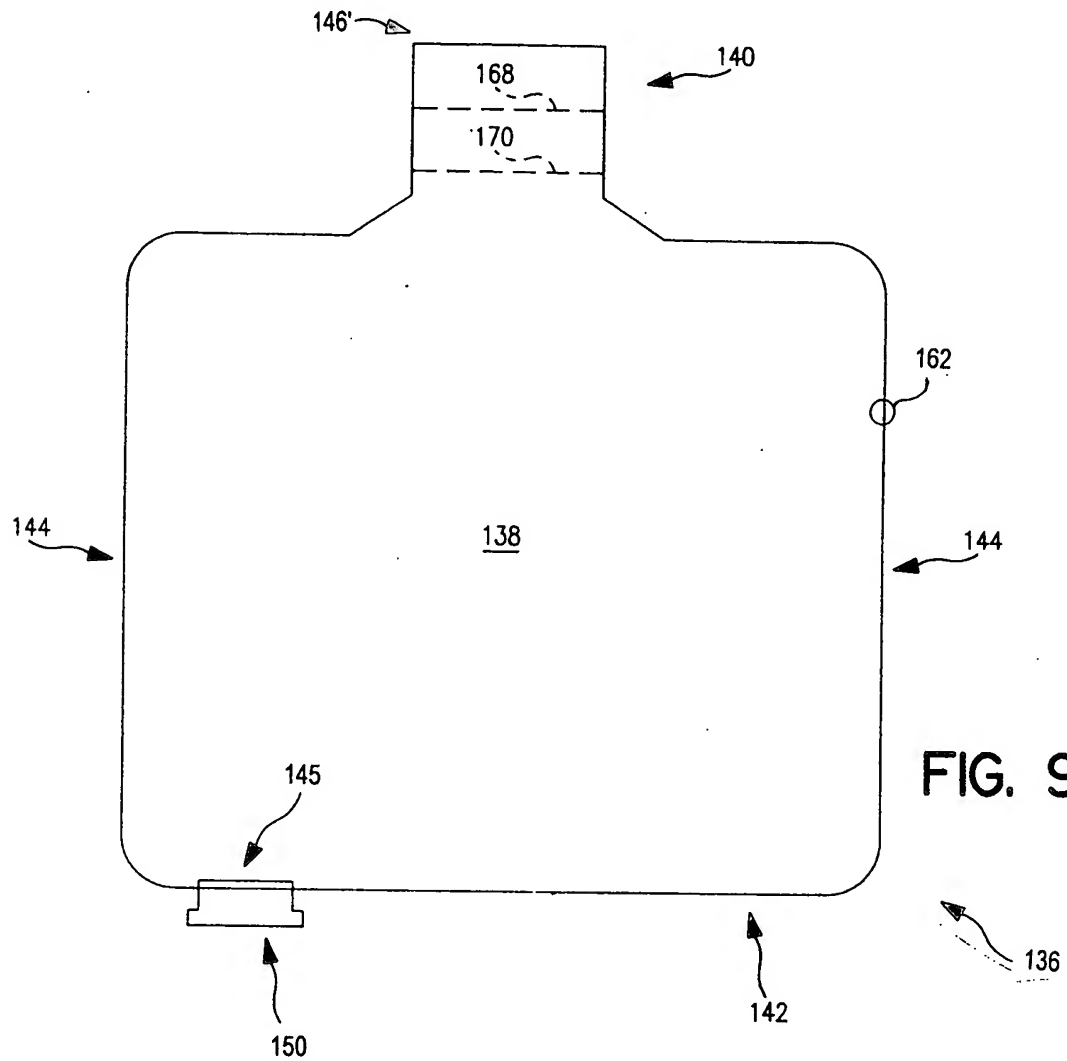


FIG. 9A

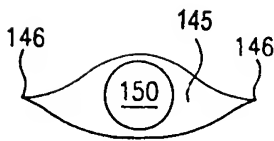


FIG. 9B

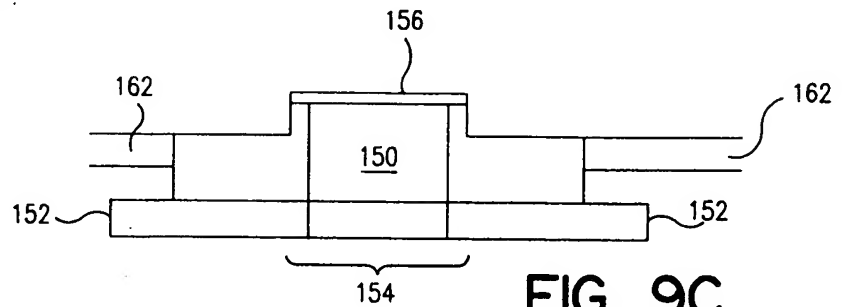


FIG. 9C

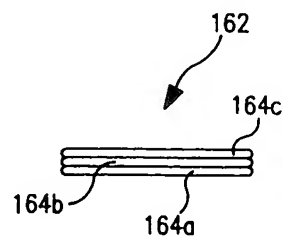


FIG. 10

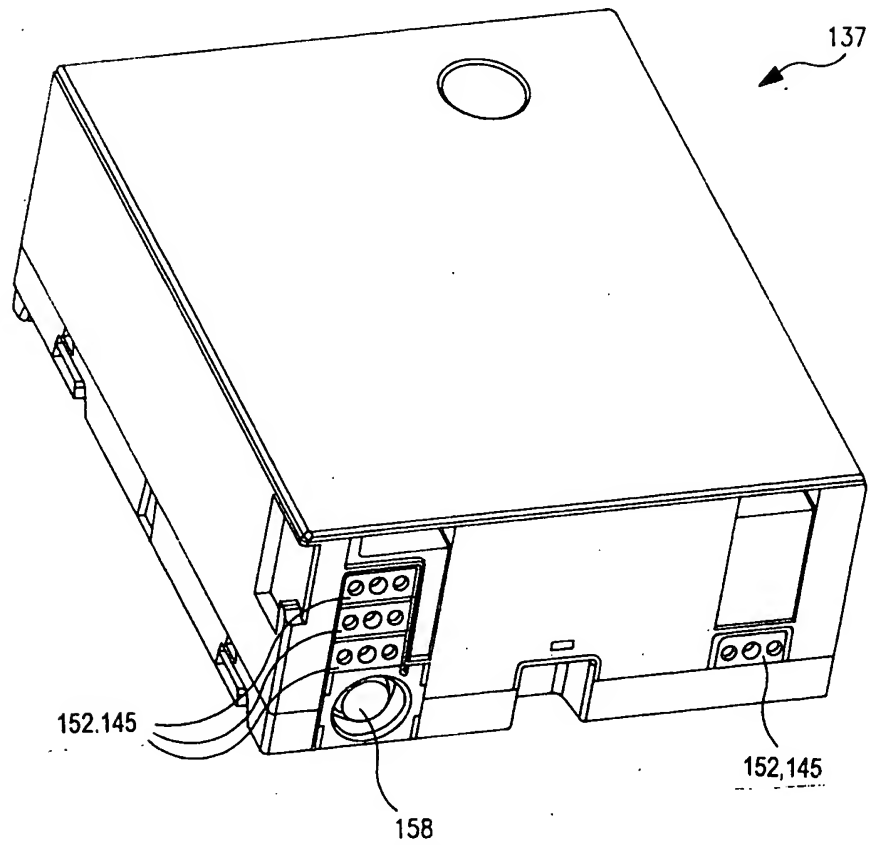


FIG. 9D

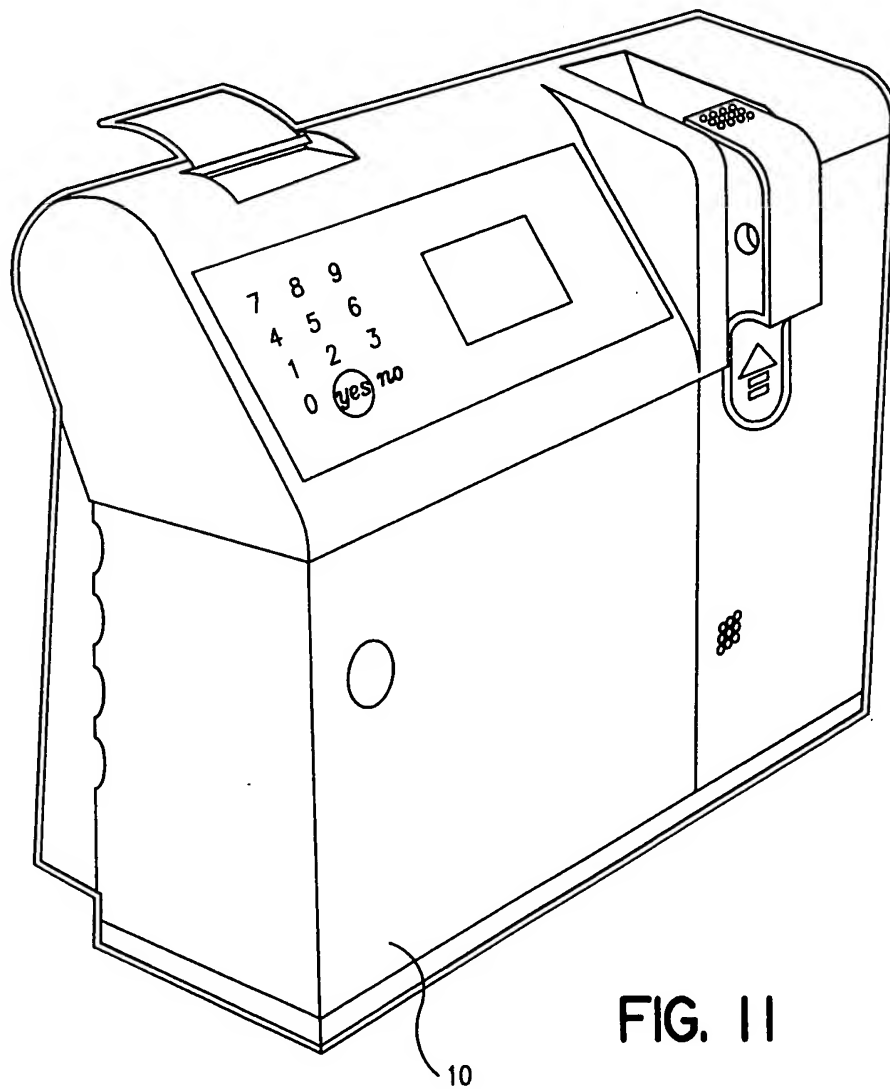


FIG. 11